इलेक्ट्रॉनिकी एवं सूचना प्रौद्योगिकी मंत्रालय
MINISTRY OF
ELECTRONICS AND
INFORMATION TECHNOLOGY

विज्ञान एवं प्रौद्योगिकी मंत्रालय
MINISTRY OF
SCIENCE AND
TECHNOLOGY

Global Electronics Association™

SMTA

IEEE

iMAPS

IESA

IEEE-IDSPS Conference

India's Global Semiconductors to Systems Conference

Converging Innovation in Semiconductors, Packaging & Systems Across 9 Key Futuristic Technologies

IDSPS 2026

Global Semiconductor Expo

📅 **Dec 6–9, 2026** | 📌 **Novotel, Visakhapatnam, India**

500+	50+	100+
Delegates	**Speakers**	**Companies**

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IDSPS
TOGETHER, WE CAN

www.ieee-idsps.in
www.idsps.in

About the Conference

Shaping the Future of Semiconductors

IEEE-IDSPS 2026 is a premier global platform bringing together leaders from academia, industry, research institutions, startups, and policy ecosystems to advance the semiconductor value chain — from chip design and fabrication to packaging and system integration.

Scheduled in Visakhapatnam, India, IDSPS 2026 aims to position India firmly on the global semiconductor map, standing alongside leading conferences across the *USA, Europe, China, Japan, and Singapore as India's flagship forum* for innovation and system-level excellence.

KEY FEATURES

What Awaits You at IDSPS 2026

PDC Courses

Expert-led Professional Development Courses on advanced semiconductor technologies.

Technical Keynotes

Keynote talks from global industry leaders shaping the semiconductor ecosystem.

Expert Panels

Panel discussions with industry & academic experts on emerging trends & challenges.

Industry Case Studies

Real-world case studies highlighting practical semiconductor innovations.

Innovation Showcase

Exhibition space for companies and startups to showcase cutting-edge tech.

Supplier Sessions

Industry suppliers presenting the latest tools, materials, and manufacturing tech.

Industry–Academia Collab

Encouraging partnerships between industry & research institutions.

Networking Opportunities

Connect with global experts, researchers, and industry leaders worldwide.

Conference Agenda

Day- 1

PDC Courses

09:00 - 11:00	Hall-A	What is Packaging? Why Advanced Packaging?
	Hall-B	Package Design and architectures
	Hall-C	Design for Reliability
11:00 - 13:00	Hall-A	Package Substrates: Lead Frame, Ceramic, Organic, Silicon and Glass
	Hall-B	RDL on Glass & Organic Substrates
	Hall-C	Opto-electronics
13:00 - 14:00	Lunch Break	
14:00 - 16:00	Hall-A	IC Assembly: From Wire Bond to Flip Chip, TCB to Hybrid Bonding
	Hall-B	Package Materials
	Hall-C	Power Components
16:00 - 18:00	Hall-A	Thermal Management of Logic & Power Devices
	Hall-B	Power Electronics
	Hall-C	Electrical Test

Supplier Sessions

10:00 – 10:30	1. Advanced Materials
10:30 – 11:00	2. EDA Tools
11:00 – 11:30	3. Substrates
11:30 – 12:00	4. Lithography Tools
12:00 – 12:30	5. Metrology Tools
12:30 – 13:00	6. Opto-Electronic Tools
14:00 – 14:30	7. Accelerated Test Tools
14:30 – 15:00	8. Passive Components
15:00 – 15:30	9. Test Tools
15:30 – 16:00	10. Panel & Through Via Tools
16:00 – 16:30	11. Assembly Tools
16:30 – 17:00	12. Thermal Materials (TIMs & Heatsinks)

Day- 2

09:00 - 11:00	Inaugural Session
11:00 - 13:00	Plenary Industry keynote Session
13:00 - 14:00	Lunch Break
14:00 - 15:00	Industry panel session
15:00 - 16:00	Global collaborators session

Conference Agenda

Technical Sessions

Day - 02

16:00 – 17:30	Advanced Packaging Architectures for High-Performance Computing
17:30 – 19:00	Reliability Challenges in Advanced Semiconductor Packaging

Day - 03

09:00 – 10:30	Advanced Glass Substrates with Through-Glass Vias (TGV)
10:30 – 12:00	Redistribution Layer Technologies on Next-Generation Substrates
12:00 – 13:30	Integrated Opto-Electronics for Next-Generation Packaging
13:30 - 14:30	Lunch Break
14:30 – 16:00	Hybrid Bonding Technologies for Advanced Semiconductor Packaging
16:30 – 18:00	Integrated Power Electronics: Trends and Packaging Innovations

Day - 04

09:00 – 10:30	Power Components: Advanced Packaging for Next-Generation Power Devices
10:30 – 12:00	Thermal Management Challenges in Advanced Semiconductor Packaging
12:00 – 13:00	Lunch Break
13:00 – 13:30	Education & Workforce Session
13:30 – 14:00	IDSPS Startups
14:00 – 15:00	Awards & Closing Ceremony

Exhibit With Us

Showcase your innovations to 500+ delegates at IEEE-IDSPS 2026

- Showcase cutting-edge products to a technically engaged semiconductor audience
- Engage directly with 500+ industry leaders, researchers, and decision-makers
- Build strategic partnerships across the semiconductor value chain
- Position your brand at India's flagship semiconductor conference

PREMIER 4M X 2M

($ 5,250 or ₹5,00,000)

4
Delegate Passes

Conference Benefits

- Prime high-visibility exhibitions
- Branded stall structure included
- 4 Complimentary delegate passes
- Social media mention
- Access to networking sessions
- Company logo on website

Stall Facilities

- 1 Info table + 3 Chairs
- 1 LED TV/ Display Screen
- 2 Power sockets
- Company logo on fascia board
- Carpeted booth + Basic light

FEATURED 3M X 2M

($ 3,150 or ₹3,00,000)

3
Delegate Passes

Conference Benefits

- Branded stall structure included
- 3 Complimentary delegate passes
- Networking access
- Company logo on website

Stall Facilities

- 1 Info table + 2 Chairs
- 1 LED TV/ Display Screen
- 1 Power sockets
- Company logo on fascia board
- Carpeted booth + Basic light

STANDARD 2M X 2M

($ 2,100 or ₹2,00,000)

2
Delegate Passes

Conference Benefits

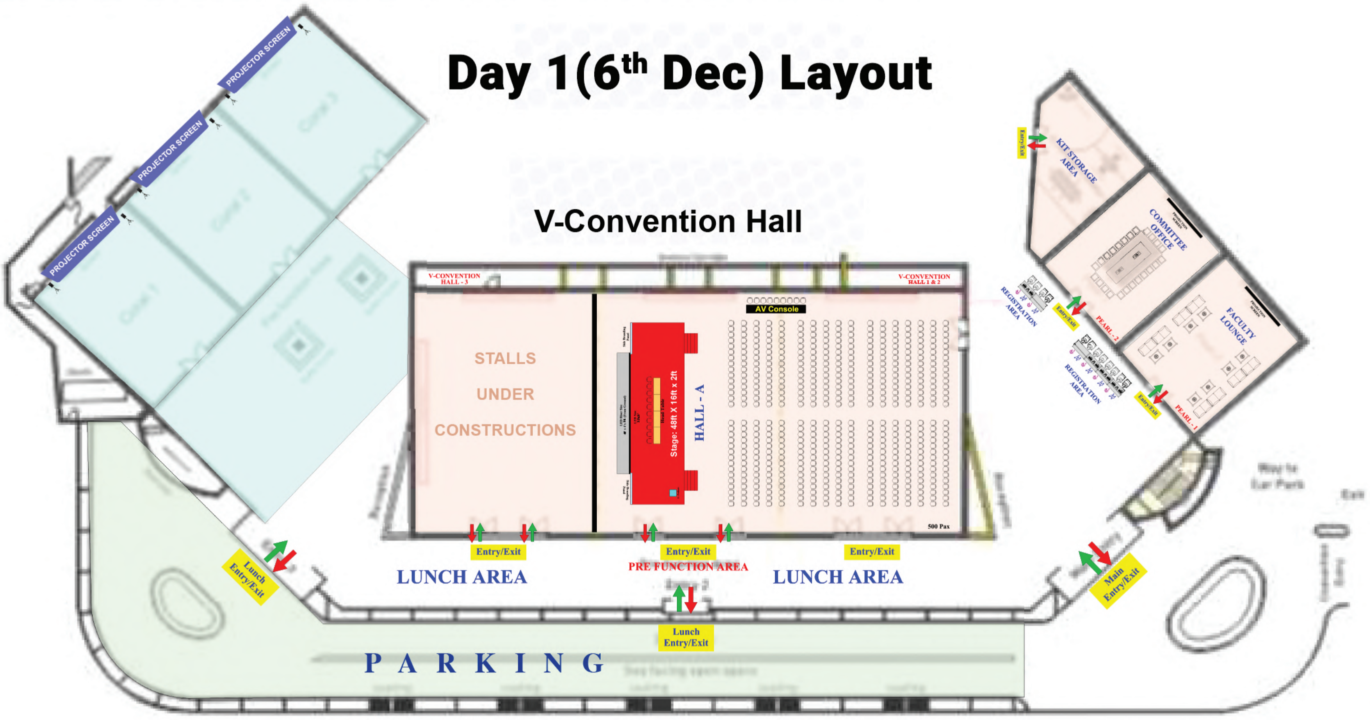
- Branded stall structure included
- 2 Complimentary delegate passes
- Interact with attendees
- Company listed on website

Stall Facilities

- 1 Info table + 2 Chairs
- 1 LED TV/ Display Screen
- 1 Power sockets
- Company logo on fascia board
- Carpeted booth + Basic light

Conference layout

Day 1(6th Dec) Layout



Day 2-4 (7th - 9th Dec) Layout

🟩	2m x 2m = 46 stalls	🟪	3m x 2m = 30 stalls	Total = 76 stalls

Practical FAQs – IEEE-IDSPS 2026 Expo

1. What is the IDSPS Expo?

The IDSPS Expo is a technology exhibition held alongside the *IEEE–IDSPS Conference 2026* , showcasing innovations in semiconductor design, advanced packaging, materials, and integrated electronic systems.

2. When and where will the IDSPS Expo take place?

The Expo will be held from *7th–9th December 2026* at *Novotel Visakhapatnam, India .*

3. Who should exhibit at the IDSPS Expo?

The expo is ideal for:

- Semiconductor companies
- Packaging and substrate manufacturers
- Electronics and materials suppliers
- Semiconductor equipment providers
- AI hardware and system technology companies
- Startups working in semiconductor and electronics innovation

4. What are the booth options available?

Exhibitors can choose from multiple booth sizes:

- Premier Booth – 4m × 2m
- Featured Booth – 3m × 3m
- Standard Booth – 2m × 2m

5. How will exhibitors benefit from participating?

Exhibitors will gain:

- Exposure to global semiconductor experts and decision-makers
- Opportunities to demonstrate new technologies
- Direct engagement with researchers, engineers, and industry leaders
- Brand visibility within the semiconductor ecosystem

6. Can exhibitors conduct product demonstrations?

Yes. Exhibitors are encouraged to showcase live product demonstrations, prototypes, and technology solutions at their booths.

7. How can companies book an exhibition booth?

Companies can secure their exhibition space by contacting the IDSPS Expo team via the official conference website or email.

8. Is there an opportunity for additional brand visibility?

Yes. Exhibitors can also explore sponsorship opportunities to increase brand visibility through conference branding, speaking opportunities, and marketing exposure.

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About IDSPS

IDSPS — the Indian Design & Semiconductors to Packaging & Systems society — is a global community dedicated to advancing the complete semiconductor value chain, from chip design through fabrication, advanced packaging, and system-level integration. IDSPS brings together *engineers, researchers, academics, and industry leaders* from across the world to collaborate, share knowledge, and drive innovation in the semiconductor ecosystem.

Our Pillars

Research & Innovation

Advancing semiconductor science through peer-reviewed research, technical paper presentations, and innovation showcases.

Industry Collaboration

Building bridges between research institutions and the global semiconductor industry for meaningful real-world impact.

Education & Development

Delivering world-class PDC courses, workshops, and certifications to upskill the next generation of engineers.

Global Community

Connecting professionals across 20+ countries to foster international partnerships and knowledge exchange.

Reach Us at

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